



Patent Application Number: 10/006,966

Attorney Docket Number: Analog.5721-4

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**APPLICANT:** Timothy R. SPOONER et al. **GROUP:** 2829  
**SERIAL NO:** 10/006,966 **EXAMINER:** S. Geyer  
**FILED:** December 5, 2001

**FOR: A METHOD AND DEVICE FOR PROTECTING MICRO  
ELECTROMECHANICAL SYSTEMS STRUCTURES  
DURING DICING OF A WAFER**

**Assistant Commissioner of Patents  
Washington, D.C. 20231**

Sir:

**AMENDMENT UNDER 37 C.F.R. 1.111**

In response to the Office Action mailed December 4, 2002, the following amendments and remarks are respectfully submitted under 37 C.F.R. 1.111 in connection with the above-identified application.

## In the Claims

Please amend the following claims:

35. (Amended) A method for protecting a MEMS structure during a dicing of a MEMS wafer to produce individual MEMS dies, comprising the steps of:

(a) fabricating a MEMS wafer having a plurality of MEMS structure sites on a first side and a plurality of through-holes on a second side;

### (b) fabricating a wafer sample

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